

## 1. General description

Silicon Carbide Schottky diode in a TO220F-2L plastic package, designed for high frequency switched-mode power supplies.

## 2. Features and benefits

- Highly stable switching performance
- High forward surge capability  $I_{FSM}$
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- Insulated package rated at 2500V RMS

## 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

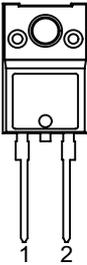
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		650			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_n \leq 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	10			A
$T_j$	junction temperature		175			$^\circ\text{C}$
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 10\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 5</a>	-	1.5	1.7	V
		$I_F = 10\text{ A}$ ; $T_j = 150\text{ }^\circ\text{C}$ ; <a href="#">Fig. 5</a>	-	1.8	2.1	V
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 10\text{ A}$ ; $di_F/dt = 500\text{ A}/\mu\text{s}$ ; $V_R = 400\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>	-	16	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	n.c.	mounting base; isolated		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
GKTSC10650X	TO220F-2L	GKTSC10650X6Q	Tube	50	TO220FN-2L	12-Jul-2015

## 7. Marking

Table 4. Marking codes

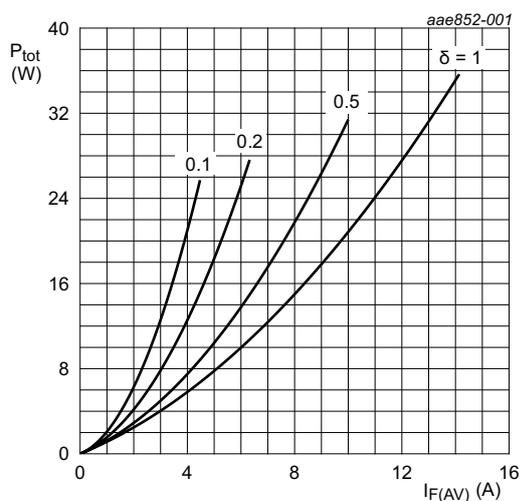
Type number	Marking codes
GKTSC10650X	GKTSC 10650X

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

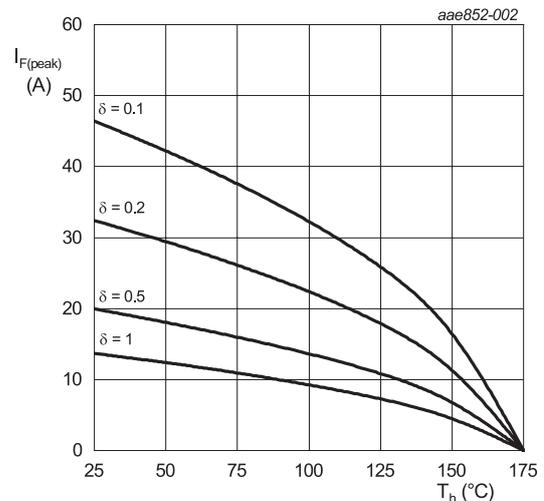
Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		650	V
$V_{RWM}$	crest working reverse voltage		650	V
$V_R$	reverse voltage	DC	650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_h \leq 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	10	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_h \leq 25\text{ }^\circ\text{C}$ ; square-wave pulse	20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse	50	A
		$t_p = 10\text{ }\mu\text{s}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; square-wave pulse	450	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; $t_p = 10\text{ ms}$	12.5	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature		-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 0.701\text{ V}; R_s = 0.131\text{ }\Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Current derating as a function of heatsink temperature**

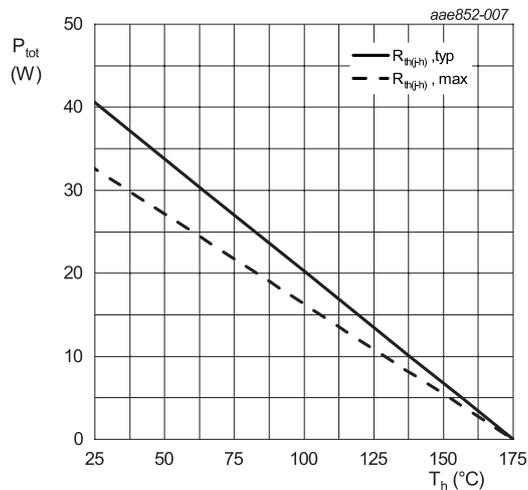


Fig. 3. Total power dissipation as a function of heatsink temperature

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to heatsink	with heatsink compound; <a href="#">Fig. 4</a>	-	3.7	4.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W

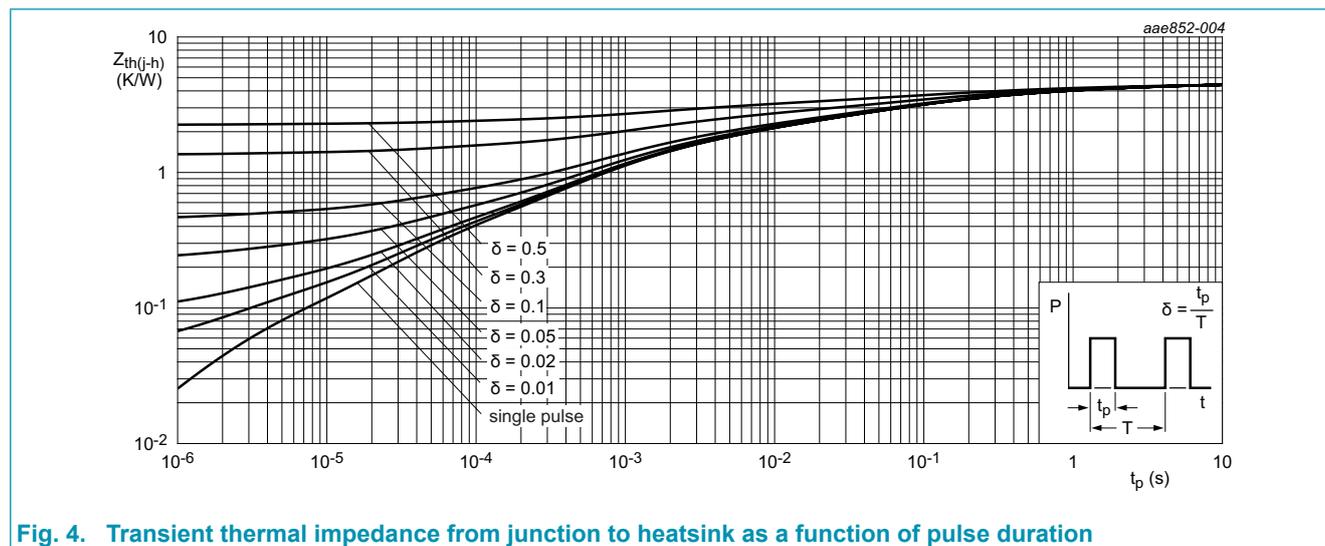


Fig. 4. Transient thermal impedance from junction to heatsink as a function of pulse duration

## 10. Isolation characteristics

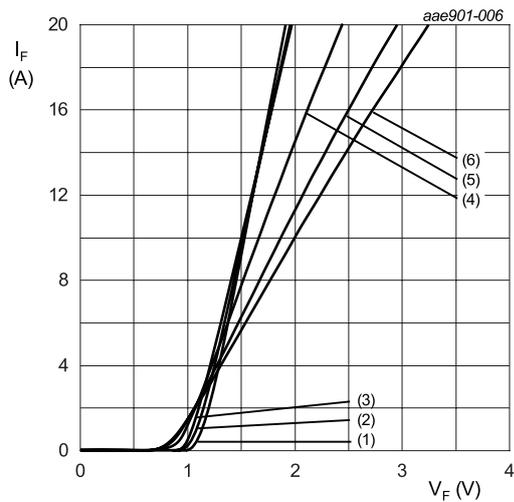
Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V

## 11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$I_F$	forward current	$I_F = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	1.5	1.7	V
		$I_F = 10 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{Fig. 5}$	-	1.8	2.1	V
$I_R$	reverse current	$V_R = 650 \text{ V}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	-	60	$\mu\text{A}$
		$V_R = 650 \text{ V}; T_j = 150 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	-	240	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 10 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 500 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	16	-	nC
$C_d$	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	328	-	pF
		$f = 1 \text{ MHz}; V_R = 300 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	44	-	pF
		$f = 1 \text{ MHz}; V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	42	-	pF
$E_{as}$	non-repetitive avalanche energy	$I_R = 5.5 \text{ A}; L = 5 \text{ mH}; T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$	75	-	-	mJ



$V_o = 0.701 \text{ V}; R_s = 0.131 \text{ } \Omega$   
 (1)  $T_j = -55 \text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_j = 0 \text{ }^\circ\text{C}$ ; typical values  
 (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; typical values  
 (4)  $T_j = 100 \text{ }^\circ\text{C}$ ; typical values  
 (5)  $T_j = 150 \text{ }^\circ\text{C}$ ; typical values  
 (6)  $T_j = 175 \text{ }^\circ\text{C}$ ; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

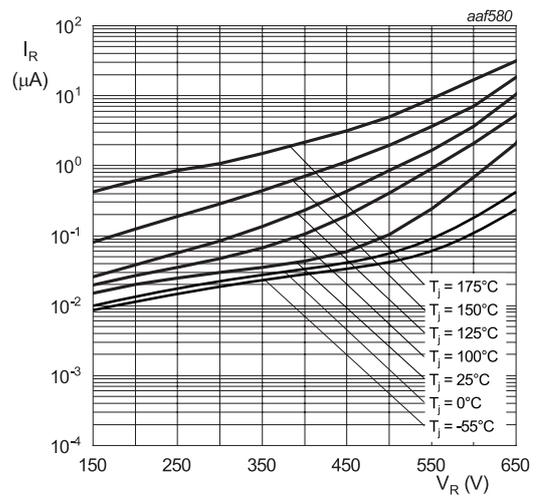
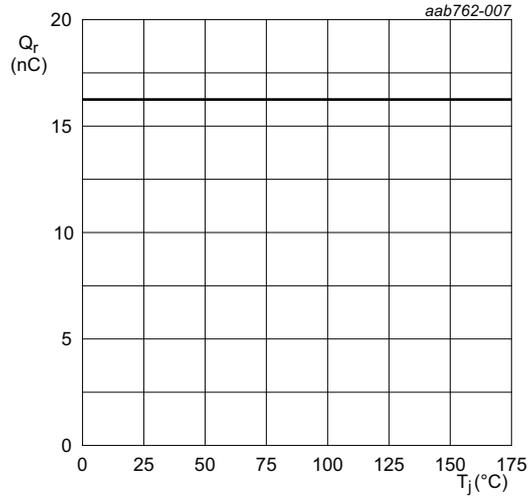


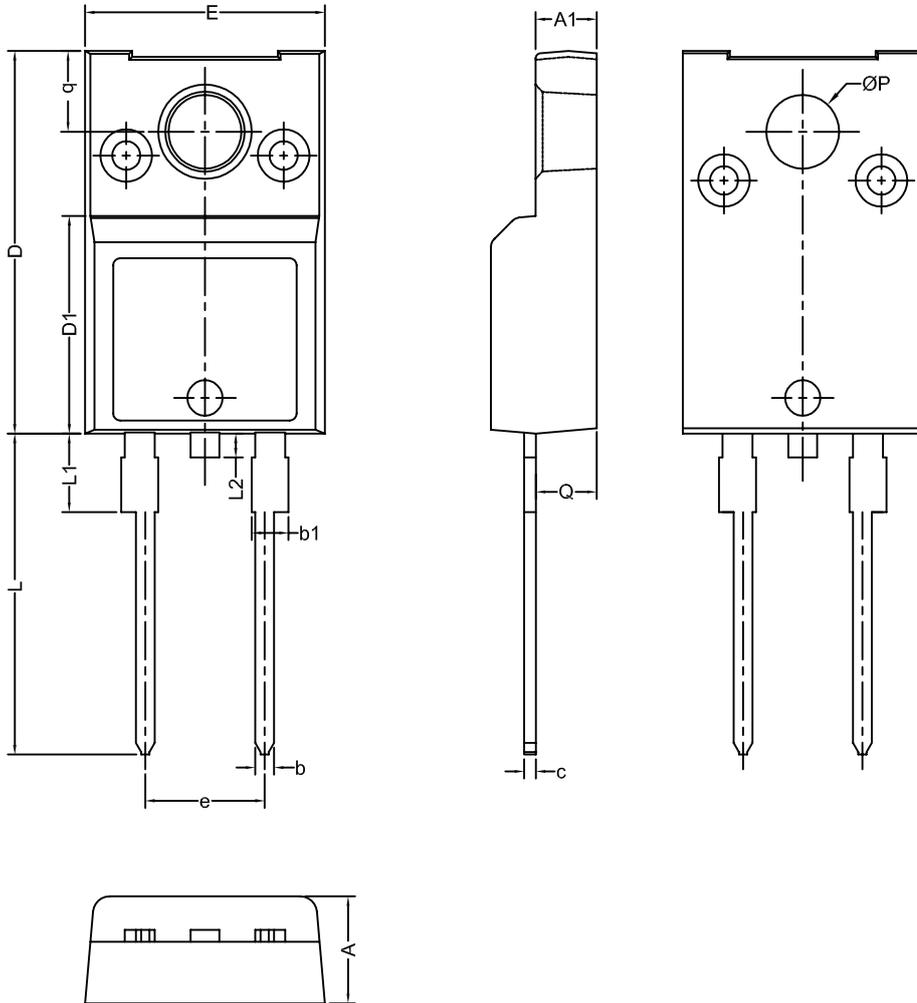
Fig. 6. Reverse leakage current as a function of reverse voltage; typical value



**Fig. 7. Recovered charge as a function of junction temperature**

**12. Package outline**

Plastic single-ended through-hole package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220F TO220F-2L



Unit	A	A1	b	b1	c	D	D1	e	E	L	L1	L2	P	q	Q
min	4.35	2.40	0.76	1.22	0.46	15.95	9.00	5.08	10.05	13.15	3.15	0.50	2.95	3.40	2.30
max	4.65	2.80	0.89	1.60	0.59	16.25	9.30	5.08 (typ)	10.35	13.85	3.45	1.00	3.25	3.40 (typ)	2.80

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
TO220F-2L		-			

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